



Journal of Engineering

Special Issue on
**Distributed Manufacturing Enabled by Cyber
Physical Systems: Framework, Model, and Practices**

CALL FOR PAPERS

In the age of Industrial Internet, modern distributed manufacturing, supported by Cyber Physical Systems (CPS), is becoming the national policies in various countries to transform their manufacturers to improve their competitiveness dramatically. Many experts from industry and research predict that this upcoming CPS will be triggered by the capabilities and technologies of enabling connected machines that work as a collaborative community. Therefore, this special issue is intended to present and to explore the frameworks, models, and practices which design and implement distributed manufacturing with CPS. Breakthrough technological developments in the area of CPS which are expected to revolutionize current manufacturing practices are invited.

Potential topics include, but are not limited to:

- ▶ Conceptual design or framework development for distributed manufacturing with CPS
- ▶ Use cases analysis for distributed manufacturing with CPS
- ▶ Surveys for distributed manufacturing with CPS
- ▶ Modeling, programming, or simulation for distributed manufacturing systems with CPS
- ▶ Big data analysis for distributed manufacturing systems
- ▶ Emerging applications with scenario analysis

Authors can submit their manuscripts via the Manuscript Tracking System at <http://mts.hindawi.com/submit/journals/je/industrial.engineering/fmop/>.

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